

REMARKS

Preliminarily, in accordance with the Examiner's request, Applicants' submit herewith a partial English translation of JP 61-50394 A as cited in the International Search Report, together with form PTO/SB/08 A & B (modified). The Examiner is respectfully requested to consider and make this reference of record by returning the initialed form. Because the indication of relevance by an "A" or "X" in the International Search Report satisfies the requirement for a concise statement of relevance of foreign language documents (as submitted on September 10, 2004), it is respectfully submitted that the \$180 fee for submitting a reference for consideration in an Information Disclosure Statement following the mailing date of a first Office Action on the merits is not required. However, if deemed necessary, the USPTO is directed and authorized to charge the \$180 fee to our Deposit Account No. 19-4880.

Review and reconsideration on merits are requested.

Claims 1-24 are rejected.

Claims 2-7, 19, and 21-24 are canceled without prejudice. Applicants present new claims 25-27 including independent claim 25 directed to a method for producing a COF flexible printed wiring board. Upon entry of the Amendment, Claims 1, 8-18, 20, and 25-27 are pending.

Review and reconsideration on the merits is respectfully requested.

The disclosure was objected to because of informalities. The Examiner asserts that on page 27, line 2, the term "patter" is in error.

Applicants have amended the specification. The term "patter" now reads --pattern--.

The drawings were objected to as failing to comply with 37 C.F.R. § 1.84(p)(4) because the reference characters 11 and 12 have both been used to designate a conductor layer as on page 31, last paragraph.

Applicants have amended the specification. The phrase “conductor layer 12” now reads --conductor layer 11--. The reference character 11 is now consistently used to designate the conductor layer. The reference character 12 is now consistently used to designate the insulating layer. No drawing changes are needed.

Claims 12-14 and 20 were rejected under 35 U.S.C. § 112, second paragraph, as being indefinite.

As to claim 12, the Examiner asserts that “the wiring pattern” lacks antecedent basis. Claim 12 has been amended to presently recite --a wiring pattern--. Antecedent basis is not needed.

As to claim 13, the Examiner asserts that the phrase “a plurality of strips of the layer correspond to the wiring patterns” is unclear. Claim 13 has been amended to presently recite --a plurality of strips corresponding to the wiring patterns--. It is clear that this phrase now refers to the plurality of strips.

As to claims 14 and 20, the Examiner asserts that claims 14 and 20 are structurally indefinite as to whether the adhesive layer is between the transfer film substrate and the transferable releasing layer. Claim 14 has been amended to presently recite that the adhesion layer is between the transfer film substrate and the transferable releasing layer. Claim 20 has

been amended to presently recite that the adhesion layer is between the film substrate and the releasing layer.

Further, the Examiner asserts that the phrase “can be exclusively released from the transferable releasing layer” is indefinite. Claims 14 and 20 have been amended so that neither of claims 14 and 20 presently recite the phrase “can be exclusively released from the transferable releasing layer.”

Claims 1-16 were rejected under 35 U.S.C. § 102(b) as being anticipated by or, in the alternative, under 35 U.S.C. § 103(a) as allegedly being obvious over U.S. Patent No. 5,281,455 to Braun *et al.* (“Braun ‘455’”) or U.S. Patent No. 5,073,422 to Konno *et al.* (“Konno ‘422’”) or U.S. Patent No. 3,554,835 to Morgan (“Morgan ‘835’”) or U.S. Patent No. 3,503,782 to Ayres (“Ayres ‘782’”).

Claim 1 presently recites that the transferable releasing layer is formed from a releasing agent comprising a silazane compound.

Braun ‘455 discloses that its releasable laminate has a fluorosilicone liner added onto a layer of a moisture-curable silicone pressure sensitive adhesive composition. The fluorosilicone release liner comprises a backing having a cured, adhesive coating. The coating includes a reaction product of (D) a fluorosilicone polymer bearing alkenyl radicals, (E) an organohydrogenpolysiloxane, and a catalyst. *See*, col. 9, line 41 to col. 10, line 3...

Konno ‘422 discloses a pressure-sensitive adhesive structure that has a pressure sensitive adhesive layer and a release agent layer. Konno ‘422 discloses that the pressure sensitive adhesive layer includes silicone pressure-sensitive adhesives. *See*, col. 5, lines 5-20. Konno

'422 discloses that the release agent layer includes a product of (a) an organopolysiloxane, (b) an organohydrogenpolysiloxane having at least three silicon bonded hydrogen atoms, and (c) a catalyst. *See*, Abstract.

Morgan '835 discloses a slidable adhesive laminate including a backing sheet 1, release dots 2, general release material 3, and a pressure sensitive adhesive 4. Morgan '835 discloses that the release dots 2 are composed of silicone. *See*, col. 1, lines 57-61. Morgan '835 discloses that the general release material 3 can be made of a silicone base release. *See*, col. 2, lines 9-16. Morgan '835 discloses that the pressure sensitive adhesive 4 may comprise GRS1011, tackifier, and an antioxidant. *See*, col. 2, lines 17-23.

Ayres '782 discloses a differential release paper including a release agent that is coated onto a paper substrate (10). Ayres '782 discloses that the release agent is an organopolysiloxane or silane, such as those shown in formulas (1) to (7). *See*, col. 2, line 69 - col. 4, line 25.

However, each of Braun '455, Konno '422, Morgan '835, and Ayres '782 fails to describe or suggest a transferable releasing layer formed from a releasing agent comprising a silazane compound as required by amended Claim 1. The organopolysiloxanes or silanes disclosed in the Braun '455, Konno '422, Morgan '835, and Ayres '782 references are not silazane compounds (i.e., hydrides of silicon and nitrogen such as HMDS containing two silicon atoms bonded to a nitrogen atom). In this regard, organopolysiloxanes are organosilicon compounds with the empirical formula R_2SiO , where R is an organic group. Silane is SiH_4 or Si_2H_6 , etc.

Thus, because Braun '455, Konno '422, Morgan '835, and Ayres '782 do not disclose the transferable releasing layer of Claim 1 formed from a releasing agent comprising a silazane compound, Claim 1 and Claims 8-16 depending therefrom are not anticipated by any of the cited references.

Moreover, the claimed transferable releasing layer is provided so as to prevent adhesion of an object thereonto, but is not provided to serve as a tacky layer after transfer as disclosed in the cited references. Thus, because the function of the transferable releasing layer is entirely different that of the prior art adhesion layers, one of ordinary skill could not readily arrive at the claimed invention from the cited references which teach organopolysiloxanes or silanes but not silazane compounds as a component of the transferable releasing layer. Thus, for these additional reasons, it is respectfully submitted that Claim 1 and Claims 8-16 dependent therefrom are also patentable over Braun '455, Konno et al., Morgan '835 or Ayres '782, considered alone or in combination thereof, and withdrawal of the foregoing rejection is respectfully requested.

Claims 17-24 were rejected under 35 U.S.C. § 103(a) as allegedly being unpatentable over Braun '455 or Konno '422 or Morgan '835 or Ayres '782.

Claim 17 presently recites that a releasing layer is provided on a surface of a film substrate and an insulating layer provided on the surface of the releasing layer opposite semiconductor chip mount side of the film substrate. In each laminate film, a transferable releasing layer and a transfer film substrate are stacked on an insulating layer. During production of COF flexible printed wiring boards (e.g., formation of a wiring pattern), the transfer film substrate serves as a reinforcing film. After the wiring board production step and in

a subsequent semiconductor chip mounting step, the transfer film substrate is peeled off, and the transferable releasing layer is transferred onto the backside of the insulating layer. Thus, adhesion of the insulating layer onto a tool for mounting semiconductor chips is advantageously prevented. In other words, if the laminate film substrate is absent, both the step of providing a reinforcing film and the step of providing a releasing layer must be performed. In accordance with the laminate film of the invention, both layers can be provided in a single step.

In contrast, each of Braun '455, Konno '422, Morgan '835, and Ayres '782 does not contemplate transfer of a releasing layer having such a releasing effect, and fails to teach or suggest a stacked laminate film for producing a COF flexible printed wiring board. Although an adhesion layer is transferred in the cited prior art, the COF flexible printed wiring board does not employ such an adhesion layer. Therefore, the prior art laminate films cannot be employed in the production of a COF flexible printed wiring board.

Moreover, it is respectfully submitted that the rejection is based on hindsight reconstruction of Applicants' claimed invention. Namely, the Office Action fails to identify where the cited prior art teaches or suggests that the laminates thereof provide for ease in processibility and transporting of a COF flexible printed wiring board. For the same reasons, a person of ordinary skill would not have been motivated to modify the laminates disclosed in Braun '455, Konno '422, Morgan '835, and Ayres '782 to form a material for producing a COF flexible printed wiring board. Further, a person of ordinary skill would have recognized that the adhesion layers disclosed in Braun '455, Konno '422, Morgan '835, and Ayres '782 cannot be

employed in the production of a COF flexible printed wiring board, which further teaches away from the present invention.

Thus, it is respectfully submitted that claim 17 is patentable over Braun '455 or Konno '422 or Morgan '835 or Ayers '782.

Claims 18 and 20 depend from Claim 17. As such, Claims 18 and 20 are not obvious for at least the same reasons as Claim 17.

Reconsideration and withdrawal of the rejection is respectfully requested.

Claims 1-24 were rejected on the ground of non-statutory obviousness-type double patenting as being unpatentable over claims 1-7 of U.S. Patent No. 6,900,989 to Sakata ("Sakata '989").

Additionally, Claims 1-24 have been provisionally rejected on the ground of non-statutory obviousness-type double patenting as allegedly being unpatentable over claims 1-4 of co-pending Application No. 10/386,116.

In response, Terminal Disclaimers are submitted herewith disclaiming the terminal part of the statutory term of any Patent granted on the instant application which would extend beyond the expiration date of the full statutory term of Sakata '989 and co-pending Application No. 10/386,116 to thereby obviate the foregoing rejections. Withdrawal is respectfully requested.

In view of the above, reconsideration and allowance of this application are now believed to be in order, and such actions are hereby solicited. If any points remain in issue which the Examiner feels may be best resolved through a personal or telephone interview, the Examiner is kindly requested to contact the undersigned at the telephone number listed below.

AMENDMENT UNDER 37 C.F.R. § 1.111
U.S. Appln. No.: 10/507,242

Docket No: Q83383

The USPTO is directed and authorized to charge all required fees, except for the Issue Fee and the Publication Fee, to Deposit Account No. 19-4880. Please also credit any overpayments to said Deposit Account.

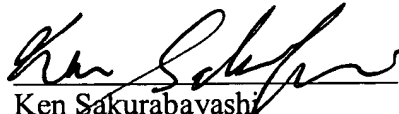
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